## **Board Stack Report** Layer Stack Stack Up **Board Layer Stack** Material Thickness Constant Name Layer Top Paste 2 Top Overlay 3 Top Solder Solder Resist 0.010mm 3.5 4 Top Layer 0.035mm Copper 5 Dielectric 1 PP-017 0.130mm 4.3 6 0.035mm Layer 1 Copper Dielectric 2 Core-025 0.203mm 4.6 8 Layer 2 Copper 0.035mm 9 Dielectric 3.1 PP-017 0.130mm 4.3 10 Dielectric 3.2 PP-017 0.130mm 4.3 11 Layer 3 Copper 0.035mm 12 Dielectric 4 Core-025 0.203mm 4.6 13 Layer 4 Copper 0.035mm 14 Dielectric 5.1 PP-017 0.130mm 4.3 15 Dielectric 5.2 PP-017 0.130mm 4.3 16 Layer 5 0.035mm Copper 17 Dielectric 6 Core-025 0.203mm 4.6 18 Layer 6 Copper 0.035mm 19 Dielectric 7 PP-017 0.130mm 4.3 0.035mm 20 **Bottom Layer** Copper 21 **Bottom Solder** Solder Resist 0.010mm 3.5 22 **Bottom Overlay** 23 **Bottom Paste** Height: 1.687mm